

- Notes:
1. Fabricate per IPC 6012 Class II
  2. Material: FR4 equivalent.  
Tg>=170°C
  3. Cu weight all layers: 1 oz.
  4. Total board thickness after plating: 0.062 +/- 10%
  5. Final finish: ENIG
  6. Soldermask both sides using photo-imagable process. Color: green
  7. Silkscreen both sides using non-conductive ink. Color : white
  8. All holes to be +/- 0.003 unless otherwise specified. Hole sizes are given after plating.
  9. Remove all burrs and sharp edges 0.015 min.

Layer Stack Legend

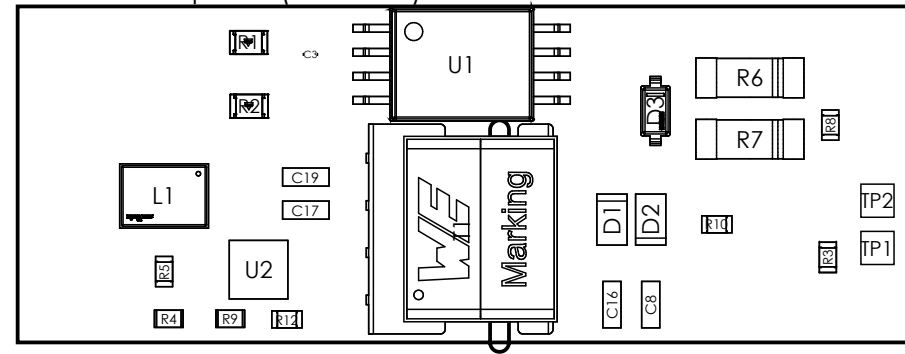
Material	Layer	Thickness	Type	Gerber
	Top Overlay		Legend	GTO
	Surface Material	0.4mil	Solder Mask	GTS
Nickel, Gold	Top Surface Finish	0.2mil	Surface Finish	
Copper	TOP	1.4mil	Signal	GTL
Prepreg		4.6mil	Dielectric	
Prepreg		3.8mil	Dielectric	
Copper	INNER1	1.4mil	Signal	G1
Core		39.0mil	Dielectric	
Copper	INNER2	1.4mil	Signal	G2
Prepreg		3.8mil	Dielectric	
Prepreg		4.6mil	Dielectric	
Copper	BOTTOM	1.4mil	Signal	GBL
Nickel, Gold	Bottom Surface Finish	0.2mil	Surface Finish	
Surface Material	Bottom Solder	0.4mil	Solder Mask	GBS
	Bottom Overlay		Legend	GBO
Total thickness: 62.4mil				

Drill Table

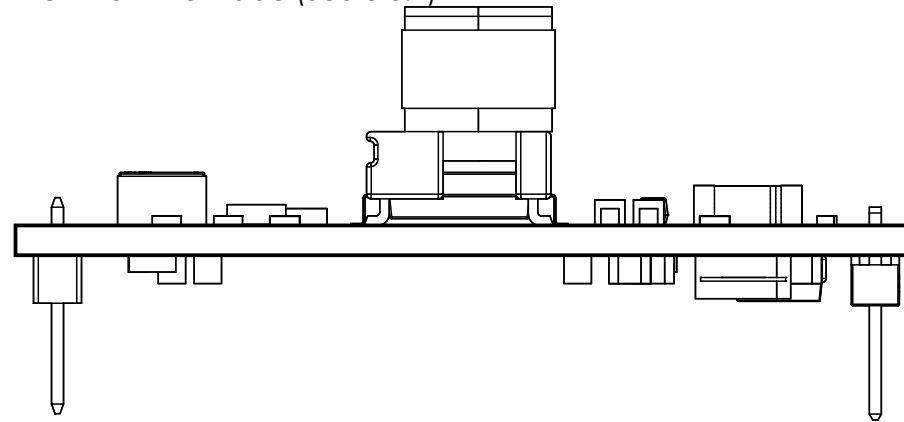
Symbol	Count	Hole Size	Plated	Hole Tolerance
□	36	0.012in	Plated	
☆	6	0.040in	Plated	
○	2	0.045in	Plated	
	44 Total			



View from Top side (Scale 5:2)



View from Front side (Scale 5:2)



View from Bottom side (Scale 5:2)

